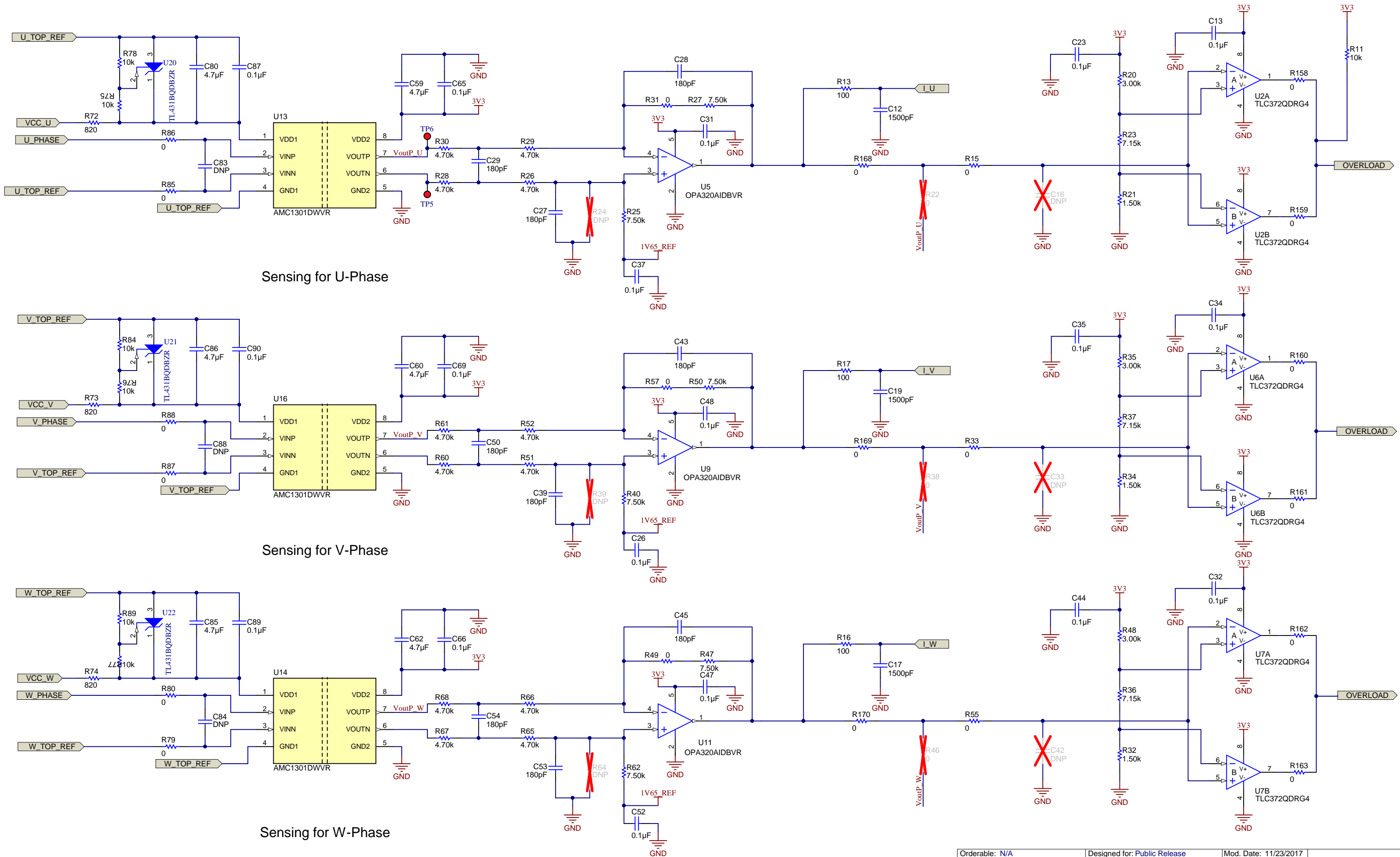


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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/9/2017
TID #: TIDA-01540	Project Title: Reinforced Isolated 3-Phase Inverter	
Number: TIDA-01540	Rev: E1	Sheet Title: Gate-drivers, IGBT module, DC Link
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 2 of 6
Drawn By: NN	File: TIDA-01540-E1_Gate driver and Module.SchDoc	Size: B
Engineer: NN/NA	Contact: http://www.ti.com/support	© Texas Instruments 2017



Sensing for U-Phase

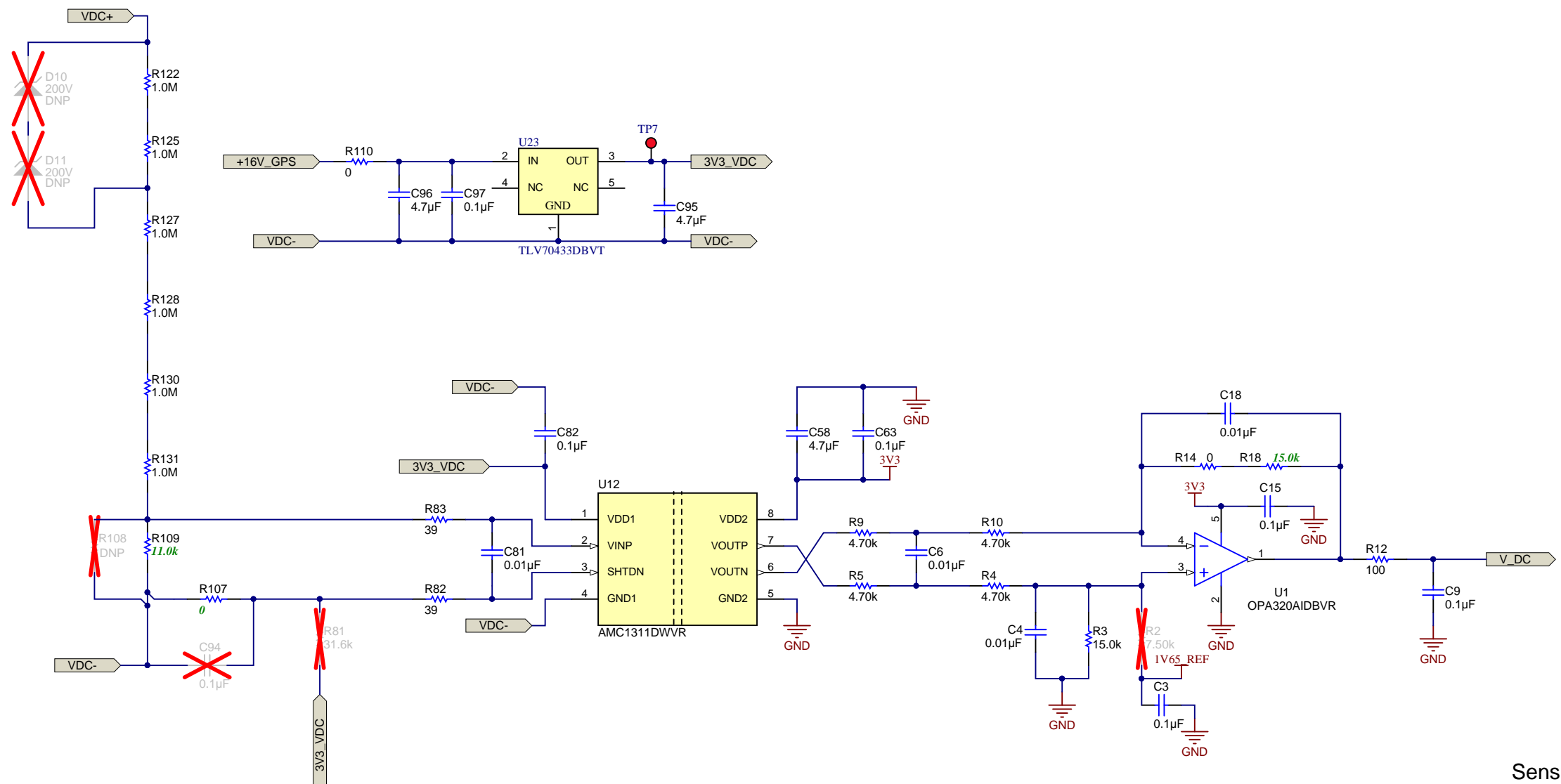
Sensing for V-Phase

Sensing for W-Phase

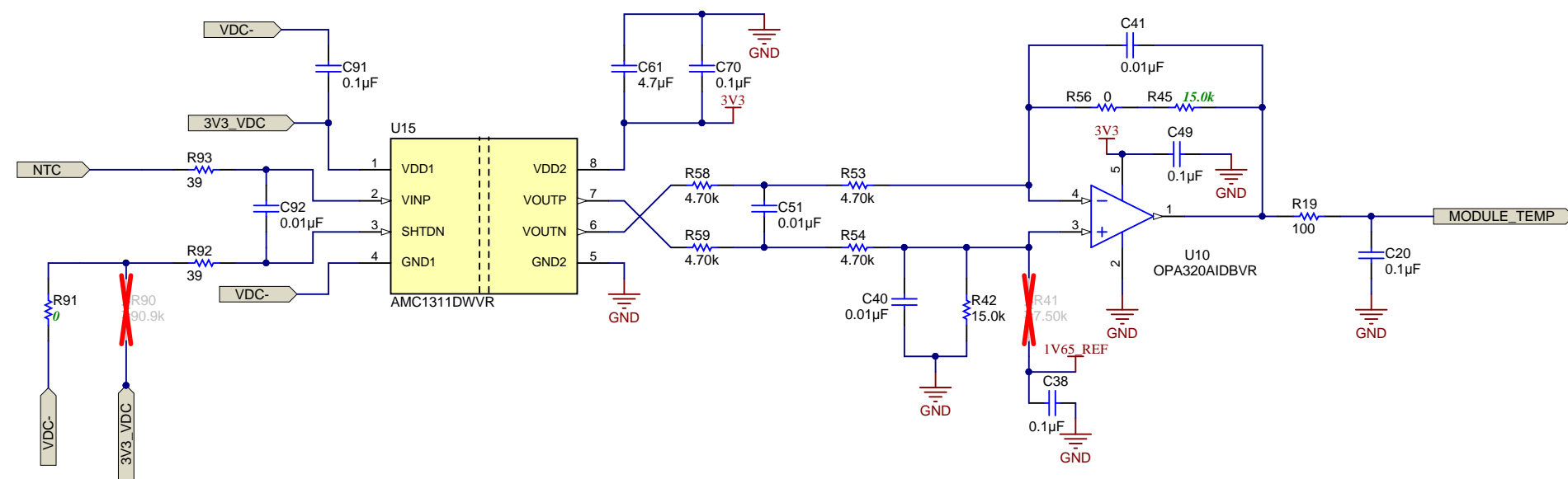
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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/23/2017
TID #: TIDA-01540	Project Title: Reinforced Isolated 3-Phase Inverter	
Number: TIDA-01540	Rev: E1	Sheet Title: Current Sense
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 3 of 6
Drawn By: NN	File: TIDA-01540-E1_Current_sense.SchDoc	Size: B
Engineer: NN/NA	Contact: http://www.ti.com/support	





Sensing for DC Link Voltage

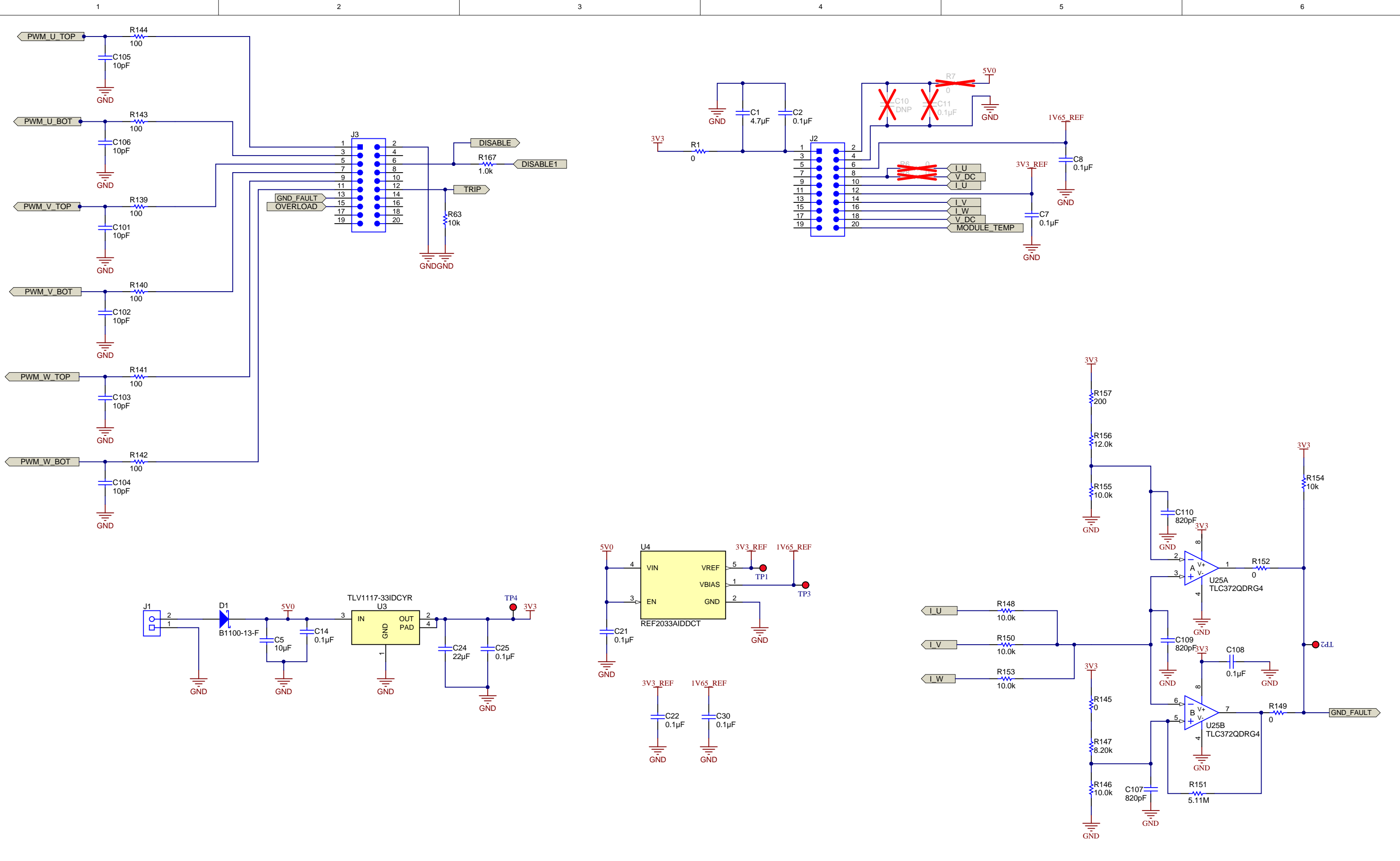


Sensing for Module Temperature

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Orderable: N/A	Designed for: Public Release	Mod. Date: 3/14/2018
TID #: TIDA-01540	Project Title: Reinforced Isolated 3-Phase Inverter	
Number: TIDA-01540	Rev: E1	Sheet Title: DC Bus and TEMP sense
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 4 of 6
Drawn By: NN	File: TIDA-01540-E1_DC BUS and TEMP Sense.Sch	Size: B
Engineer: NN/NA	Contact: http://www.ti.com/support	





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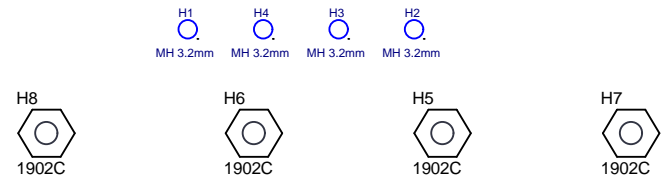
Orderable: N/A	Designed for: Public Release	Mod. Date: 11/23/2017
TID #: TIDA-01540	Project Title: Reinforced Isolated 3-Phase Inverter	
Number: TIDA-01540	Rev: E1	Sheet Title: MCU Interface
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 5 of 6
Drawn By: NN	File: TIDA-01540-E1_MCU Interface.SchDoc	Size: B
Engineer: NN/NA	Contact: http://www.ti.com/support	



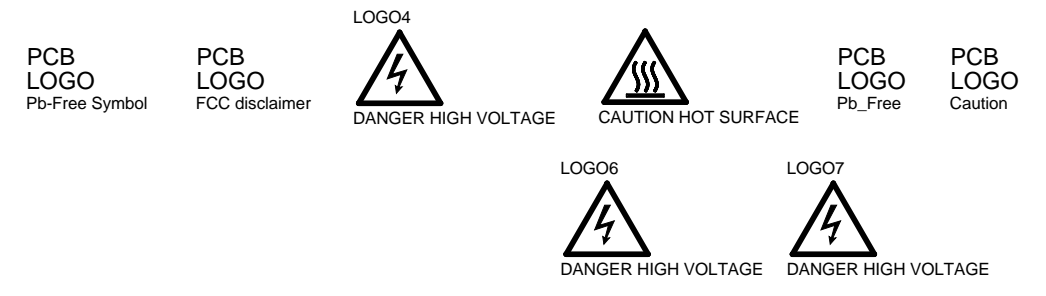
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A

A



PCB Number: TIDA-01540
PCB Rev: E1



B

B

Variant/Label Table	
Variant	Label Text
001	AMC1311 for DC_Link
002	AMC1301 for DC_Link

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

D

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